ON Semiconductor



Final Product/Process Change Notification
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eliability Data Summary:				
Test	Specification	n Condition	Interval	Results
HTOI			1008 hrs	0/77
	JESD22-A108	S IJ=125°C, Vcc=operating max	1000 hm	0/77
HTSL	JESD22-A108 JESD22-A103	IJ=125°C, Vcc=operating max Ta= 150°C	TOOR ULS	0/77
HTSL THB	JESD22-A108 JESD22-A103 JESD22-A101	IJ=125°C, Vcc=operating max I Ta= 150°C I 85°C, 85% RH, V= operating max	1008 hrs	8,,,,
	JESD22-A108 JESD22-A103 JESD22-A101	IJ=125°C, Vcc=operating max Ta= 150°C L 85°C, 85% RH, V= operating max	1008 hrs	0,11
HTSL THB ACKAGE :WLCSP36 Test	JESD22-A108 JESD22-A103 JESD22-A101 Specification	IJ=125°C, Vcc=operating max Ta= 150°C L 85°C, 85% RH, V= operating max Condition	1008 hrs	Results